

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Tetsujiro KONDO</td><td>12/27/2006</td></tr><tr><td>Tetsushi KOKUBO</td><td>12/28/2006</td></tr><tr><td>Kenji TANAKA</td><td>12/29/2006</td></tr><tr><td>Hitoshi MUKAI</td><td>01/05/2007</td></tr><tr><td>Kazumasa TANAKA</td><td>12/28/2006</td></tr><tr><td>Hirofumi HIBI</td><td>12/28/2006</td></tr></tbody></table>	Name	Execution Date	Tetsujiro KONDO	12/27/2006	Tetsushi KOKUBO	12/28/2006	Kenji TANAKA	12/29/2006	Hitoshi MUKAI	01/05/2007	Kazumasa TANAKA	12/28/2006	Hirofumi HIBI	12/28/2006	
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Kazumasa TANAKA	12/28/2006														
Hirofumi HIBI	12/28/2006														
RECEIVING PARTY DATA															
Name:	SONY CORPORATION														
Street Address:	7-35 Kitashinagawa 6-Chome														
City:	Shinagawa-Ku, Tokyo														
State/Country:	JAPAN														
Postal Code:	141-0001														
PROPERTY NUMBERS Total: 1															
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11627567</td></tr></tbody></table>	Property Type	Number	Application Number:	11627567											
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Application Number:	11627567														
CORRESPONDENCE DATA															
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ATTORNEY DOCKET NUMBER:	302459US8														
NAME OF SUBMITTER:	Meselech Amossa														

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PATENT

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REEL: 018813 FRAME: 0956

Total Attachments: 3

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**PATENT**

**REEL: 018813 FRAME: 0957**

Docket Number: \_\_\_\_\_

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in  
IMAGE FORMING APPARATUS AND METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: \_\_\_\_\_, Filing Date: \_\_\_\_\_.

This assignment executed on the dates indicated below.

Tetsujiro KONDO  
 Name of first or sole inventor

Dec. 27, 2006  
 Execution date of U.S. Patent Application

Tokyo, Japan  
 Residence of first or sole inventor

Tetsujiro Kondo  
 Signature of first or sole inventor

Dec. 27, 2006  
 Date of this assignment

Tetsushi KOKUBO

December 28, 2006

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Tetsushi Kokubo

December 28, 2006

Signature of second inventor

Date of this assignment

Kenji TANAKA

DEC 29, 2006

Name of third inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

KENJI TANAKA

DEC 29, 2006

Signature of third inventor

Date of this assignment

Hitoshi MUKAI

Jan 5, 2007

Name of fourth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fourth inventor

Hitoshi Mukai

Jan 5, 2007

Signature of fourth inventor

Date of this assignment

Kazumasa TANAKA

Dec. 28, 2006

Name of fifth inventor

Execution date of U.S. Patent Application

Chiba, Japan

Residence of fifth inventor

Kazumasa Tanaka

Dec. 28, 2006

Signature of fifth inventor

Date of this assignment

Hirofumi HIBI	December 28, 2006
Name of sixth inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of sixth inventor	
Hirofumi Hibi	December 28, 2006
Signature of sixth inventor	Date of this assignment

Name of seventh inventor	Execution date of U.S. Patent Application
Residence of seventh inventor	
Signature of seventh inventor	Date of this assignment

Name of eighth inventor	Execution date of U.S. Patent Application
Residence of eighth inventor	
Signature of eighth inventor	Date of this assignment

Name of ninth inventor	Execution date of U.S. Patent Application
Residence of ninth inventor	
Signature of ninth inventor	Date of this assignment